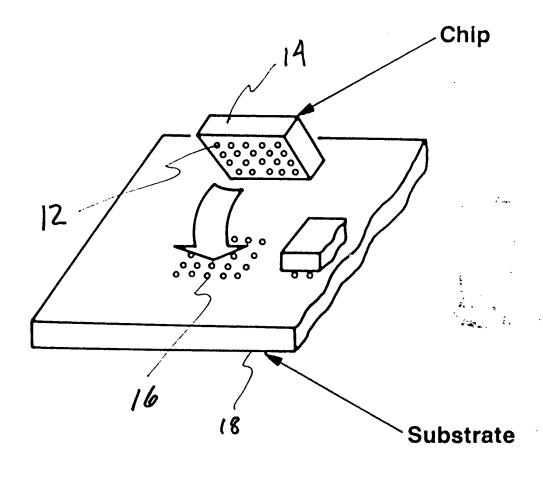
FIGURE 1 (PRIOR MRT)

y



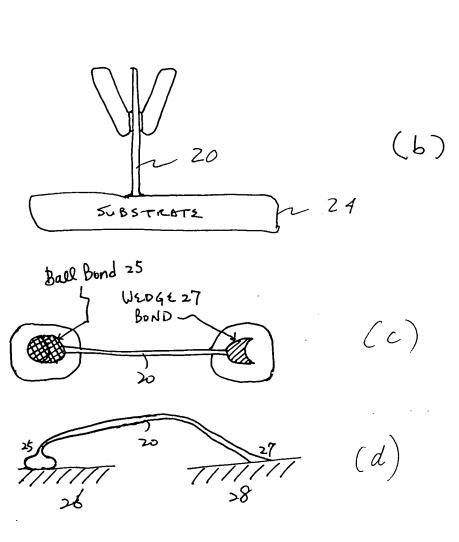
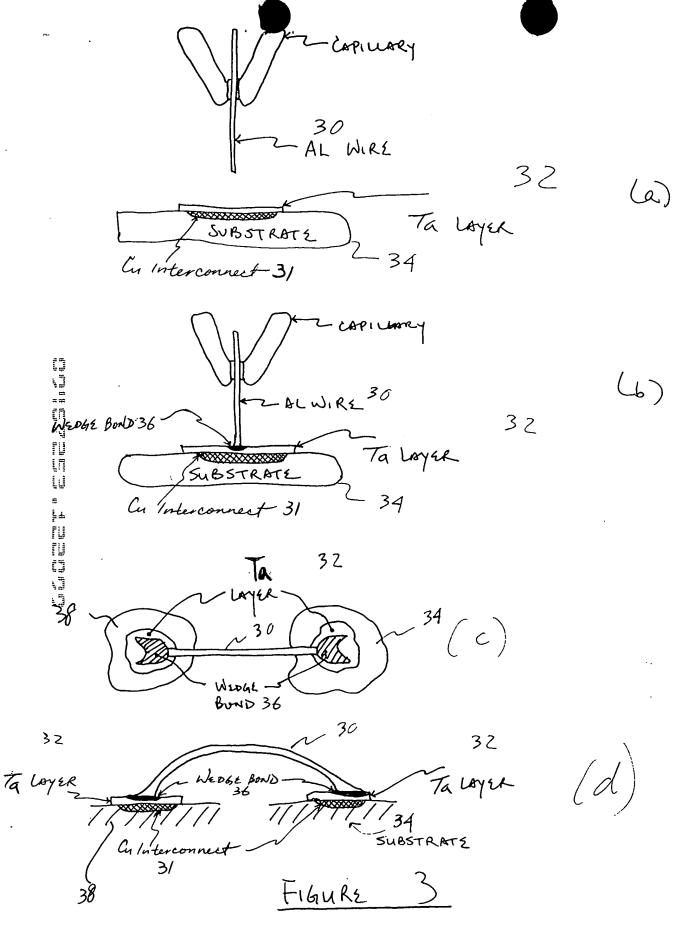


FIGURE 2 (PRIOR ART)

the of the state o

4... the gray west with the



STORT Form Substrate with Cu iterconnect 401 Fabricate in bond pad Deposit Ta laye Pattern and etch Ta layer Wedge hand onto Ta layer 405 Form Tall, Compa Form bond with substrate

FIGURE 4

Passivation (a) SUBSTRATE 52 Al Wire 56 (6) Wedge Bund 58 SUBSTRATE 52 Bondon 50

FIGURE 5